

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hirotooshi Ichikawa</td> <td>04/13/2009</td> </tr> <tr> <td>Yoshihiro Maeda</td> <td>04/13/2009</td> </tr> <tr> <td>Fusao Ishii</td> <td>04/13/2009</td> </tr> </tbody> </table>		Name	Execution Date	Hirotooshi Ichikawa	04/13/2009	Yoshihiro Maeda	04/13/2009	Fusao Ishii	04/13/2009
Name	Execution Date								
Hirotooshi Ichikawa	04/13/2009								
Yoshihiro Maeda	04/13/2009								
Fusao Ishii	04/13/2009								
RECEIVING PARTY DATA									
Name:	Silicon Quest Kabushiki-Kaisha								
Street Address:	1588-128 Koshigoe Kamakura-Shi								
City:	Kanagawa-Ken, 248-0033								
State/Country:	JAPAN								
Name:	Olympus Corporation								
Street Address:	Shinjukumonolith, 3-1 Nishi-Shinjuku 2-chome								
City:	Shinjuku-ku, Tokyo 163-0914								
State/Country:	JAPAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12590754</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12590754				
Property Type	Number								
Application Number:	12590754								
CORRESPONDENCE DATA									
Fax Number:	(650)949-4118								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Email:	BoInLin@aol.com								
Correspondent Name:	Bo-In Lin								
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Address Line 4:	Los Altos Hills, CALIFORNIA 94022								
ATTORNEY DOCKET NUMBER:	SQ-0751								
NAME OF SUBMITTER:	Bo-In Lin								

CH \$40.00 12590754

501027646

PATENT
REEL: 023581 FRAME: 0878

Total Attachments: 3

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INVENTOR
AND CITY

Whereas, I **Yoshihiro Maeda** of
Hachioji, Tokyo, Japan

have invented:

TITLE

Structural Body Electrically Connected Via
Semiconductor Material Layer

DATE
INVENTOR
SIGNED THE
DECLARATION

and executed a United States patent application therefor
on

April 13, 2009

Whereas, **Olympus Corporation** having a place of business at
Tokyo, Japan, (hereinafter called **Olympus**), desires to acquire the
entire right, title and interest of said application and invention, and to
any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is
hereby acknowledged, I, the above named, hereby sell, assign, and
transfer to **Olympus**, its successors and assigns, the entire right, title
and interest in the said application and invention therein disclosed for
the United States and foreign countries, and all rights of priority
resulting from the filing said United States application, and I request
the Commissioner of Patents to issue any Letters Patent granted upon
the inventions set forth in said application to **Olympus** its successors
and assigns; and I hereby agree that **Olympus** may apply for foreign
Letters Patent on said invention and I will execute all papers
necessary in connection with the United States and foreign
applications when called upon to do so by

CITY AND
DATE

Signed and Sealed at Tokyo, Japan
on 4/13/09

Yoshihiro Maeda

SIGNATURE OF INVENTOR

ASSIGNMENT

INVENTOR
AND CITY

Whereas, I, **Fusao Ishii** of **4405 Bayard Street**
Pittsburgh, Pennsylvania, 15213

have invented:

TITLE:

**Structural Body Electrically Connected Via Semiconductor
Material Layer**

DATE INVENTOR and executed a United States patent application therefor
SIGNED THE
DECLARATION on 4/13/09;

Whereas, **Silicon Quest Kabushiki-Kaisha**, having a place of
business at **Kamakura, Japan**, (hereinafter called **Silicon Quest**), desires
to acquire the entire right, title and interest of said application and
invention, and to any United States and foreign patents to be obtained
therefor;

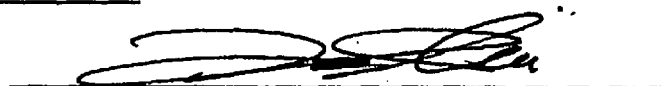
Now therefore, for a valuable consideration, receipt whereof is
hereby acknowledged, I, the above named, hereby sell, assign, and
transfer to **Silicon Quest**, its successors and assigns, the entire right, title
and interest in the said application and invention therein disclosed for
the United States and foreign countries, and all rights of priority
resulting from the filing said United States application, and I request the
Commissioner of Patents to issue any Letters Patent granted upon the
inventions set forth in said application to **Silicon Quest** its successors
and assigns; and I hereby agree that **Silicon Quest** may apply for
foreign Letters Patent on said invention and I will execute all papers
necessary in connection with the United States and foreign applications
when called upon to do so by

CITY AND

Signed and Sealed **Pennsylvania, USA**

DATE

on 4/13/09.



SIGNATURE OF INVENTOR

PATENT